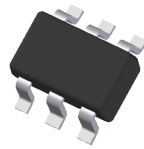


Features

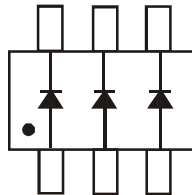
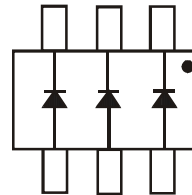
- Low Forward Voltage Drop
- Guard Ring Die Construction for Transient Protection
- Ideal for low logic level applications
- Low Capacitance
- **Lead Free/RoHS Compliant (Note 3)**
- **"Green" Device, Note 4 and 5**

Mechanical Data

- Case: SOT-26
- Case Material: Molded Plastic, "Green" Molding Compound, Note 5. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Polarity: See Diagram
- Leads: Matte Tin (Lead Free), Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Copper leadframe).
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.016 grams (approximate)



Top View


 SDM03MT40
Device Schematic

 SDM03MT40A
Device Schematic

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	40	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_R		
RMS Reverse Voltage	$V_{R(RMS)}$	28	V
Forward Continuous Current (Note 2)	I_{FM}	30	mA
Non-Repetitive Peak Forward Surge Current @8.3ms Single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	200	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P_D	225	mW
Thermal Resistance, Junction to Ambient Air	$R_{\theta JA}$	444	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-40 to +125	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	$V_{(BR)R}$	40	—	—	V	$I_R = 10\mu\text{A}$
Forward Voltage Drop (Note 1)	V_F	—	—	370	mV	$I_F = 1\text{mA}$
Leakage Current (Note 1)	I_R	—	—	1	μA	$V_R = 10\text{V}$
Total Capacitance	C_T	—	2	—	pF	$V_R = 1\text{V}$ $f = 1.0\text{MHz}$

- Notes:
1. Short duration pulse test used to minimize self-heating effect.
 2. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 3. No purposefully added lead.
 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 5. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
 6. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).

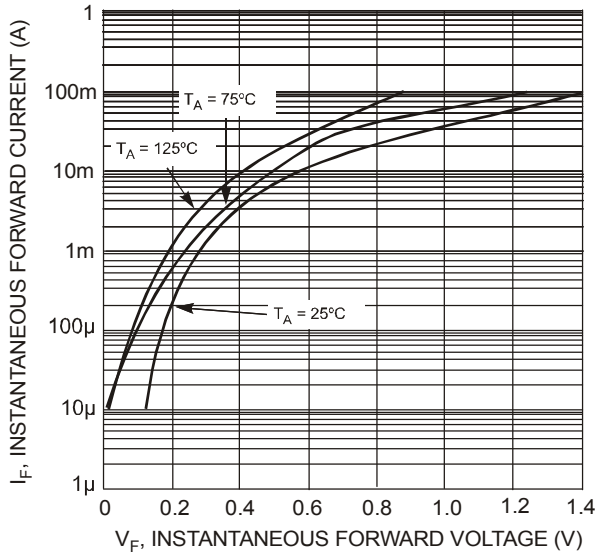


Fig. 1 Typical Forward Characteristics

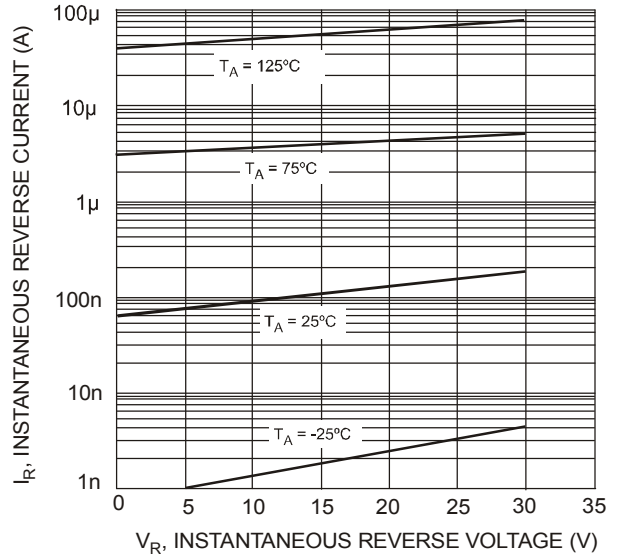


Fig. 2 Typical Reverse Characteristics

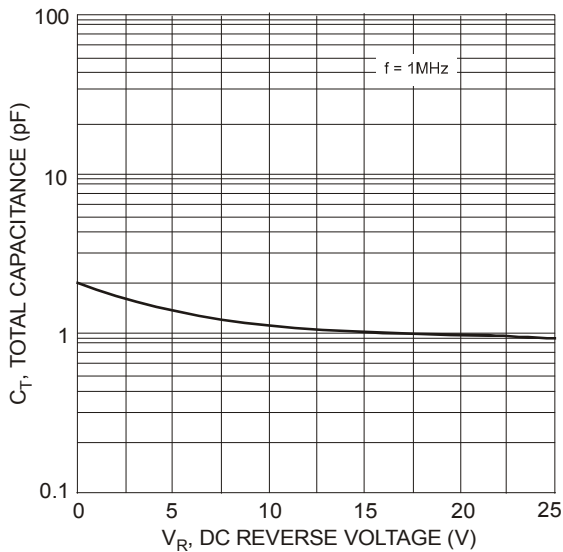


Fig. 3 Total Capacitance vs. Reverse Voltage

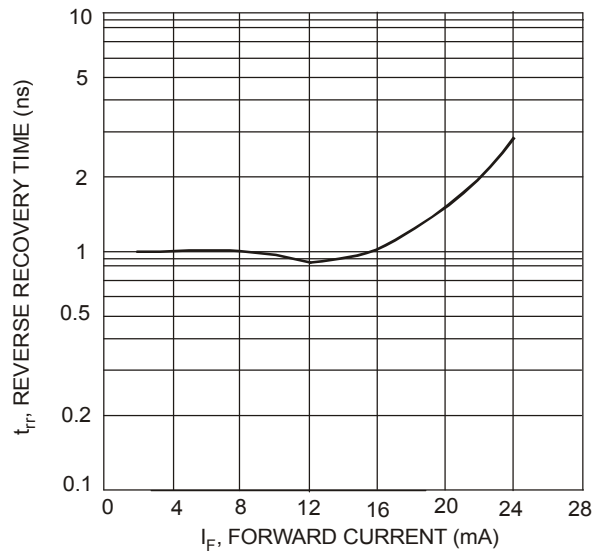


Fig. 4 Typical Reverse Recovery Time Characteristics

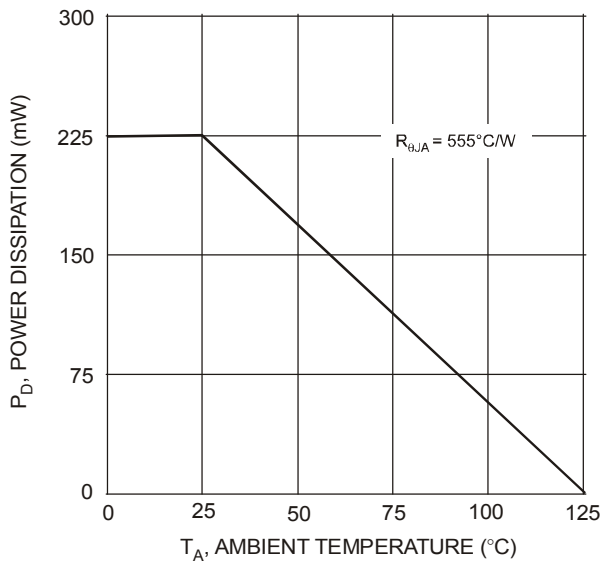


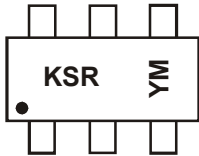
Fig. 5 Power Derating Curve

Ordering Information (Notes 4 & 7)

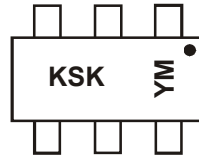
Part Number	Case	Packaging
SDM03MT40-7-F	SOT-26	3000/Tape & Reel
SDM03MT40A-7-F	SOT-26	3000/Tape & Reel

Notes: 7. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



KSR = SDM03MT40 Product Type
 Marking Code (See Note 6)
 YM = Date Code Marking
 Y = Year ex: T = 2006
 M = Month ex: 9 = September



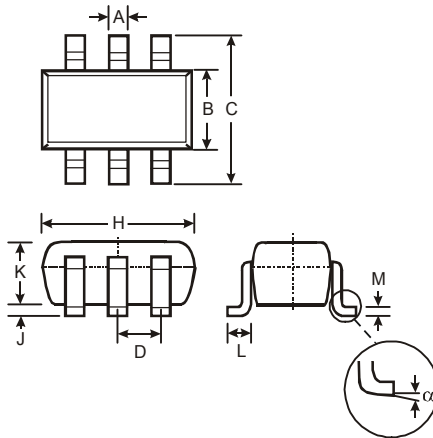
KSK = SDM03MT40A Product Type
 Marking Code (See Note 6)
 YM = Date Code Marking
 Y = Year ex: T = 2006
 M = Month ex: 9 = September

Date Code Key

Year	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	T	U	V	W	X	Y	Z	A	B	C

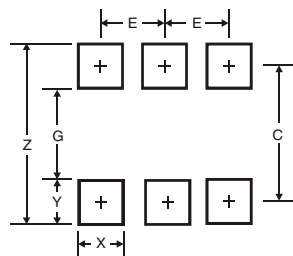
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C	2.40
E	0.95

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